**21st Annual CMSE  
Components for Military & Space Electronics  
Training & Exhibition  
   
April 11-13th, 2017  
Sheraton Four Points Hotel (LAX)  
Los Angeles, California**  
  
  
**Call for Presentation Outline**  
  
***The Premier Event on the engineering, design, reliability,  
and application of Electronic Components in Military & Space Systems*  
  
  You are requested to submit an outline for a presentation\* at CMSE on topics such as:**

* Hermeticity and the new Spec Limits
* Reliability issues 2D & 3D FO-WLP
* Future of QML hermetic ICs
* Radiation Effects and Testing
* EOL and Obsolescence Issues
* GaN and SiC for RF and high temp
* COTS insertion success stories and challenges
* IC Copper wire bonding & reliability
* Issues with QFN & CS packages
* BME/PME MLCCs for hi-rel applications
* New technology for capacitors, resistors, relays
* Secure Electronics (anti-tampering)
* Challenges of Non-Hermetic Packages
* Life cycle Component Sourcing & Verification

Please email your presentation outline to [CMSE@tjgreenllc.com](mailto:CMSE@tjgreenllc.com?subject=21st%20Annual%20CMSE%20-%20Presentation%20Outline%20)

**Deadline for Submission: November 18, 2016**

Technical Co-Chairs:

Tom Green and Leon Hamiter

Exhibits Chair:

Tom Terlizzi



Organized by:  
[TJ Green Associates LLC](http://www.tjgreenllc.com/)

\*Presentations are typically 20 minutes or so with 5 minutes of Q & A. This is not a formal paper submission and you can decide how much of the presentation material you would like to include and make available to the attendee. The idea is to promote sharing of basic scientific and technical information about common problems faced by both the component manufacturer and the system OEM.